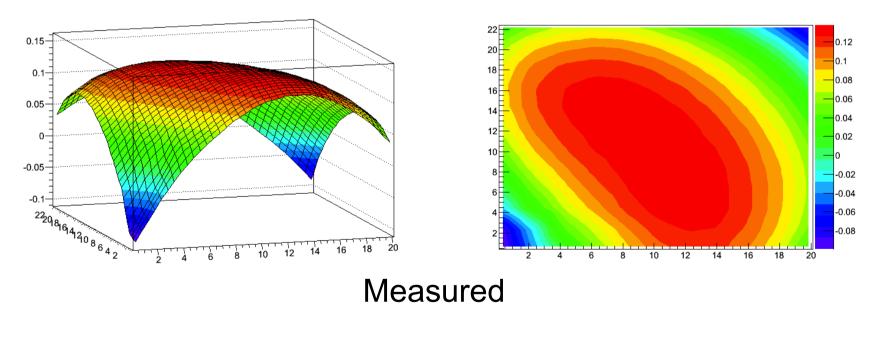
HFT Pixel Chip Survey Fit

Qiu Hao



TPS, pol2, pol3 methods to fit

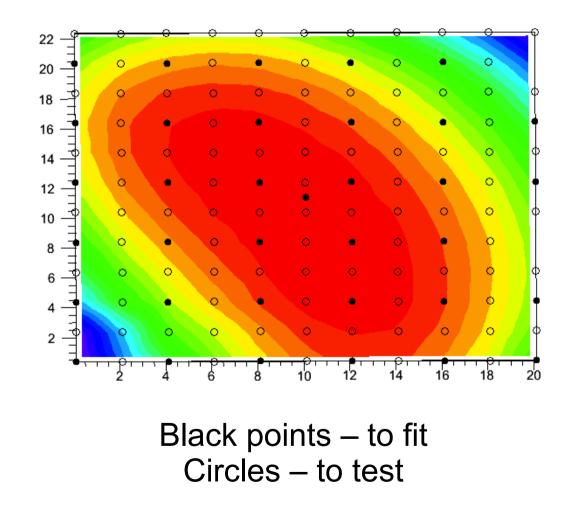
1

TPS Method

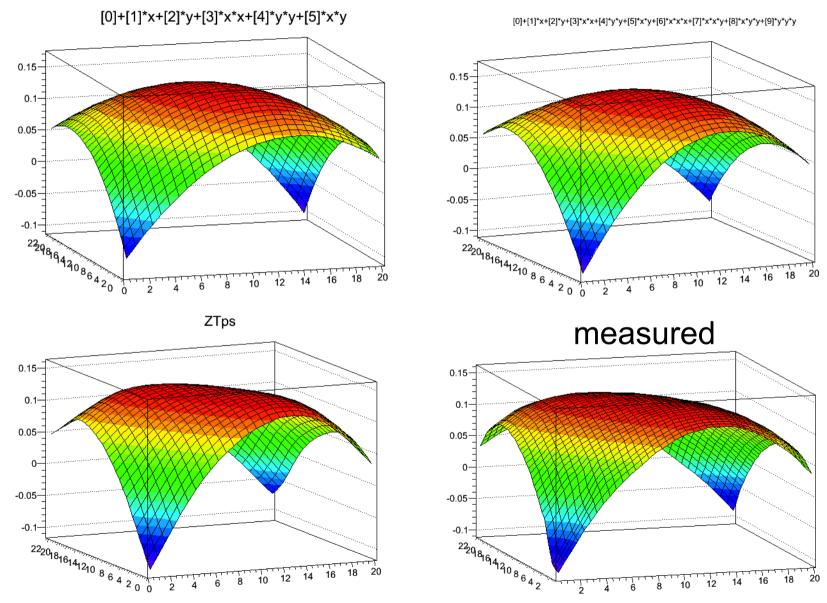
Found and realized in VC by Xiangming, rewriten in ROOT

thin plate spline minimize the "bending energy", defined by $I(f) = \iint (f_{xx}^2 + 2f_{xy}^2 + f_{yy}^2) dxdy$ R^2 4.5 4.5 4 4-3.5-3.5-3-3-2.5-2.5 2-2-1.5-1.5

Points to fit and to test

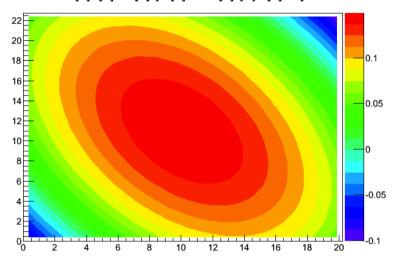


Fit Result 3D

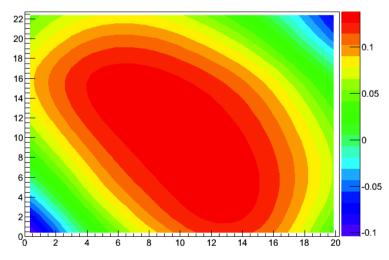


Fit Result 2D

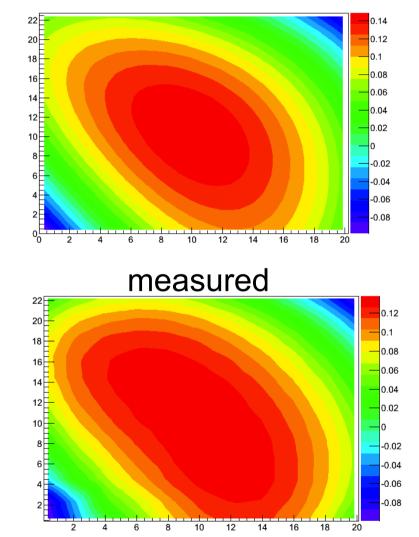
[0]+[1]*x+[2]*y+[3]*x*x+[4]*y*y+[5]*x*y

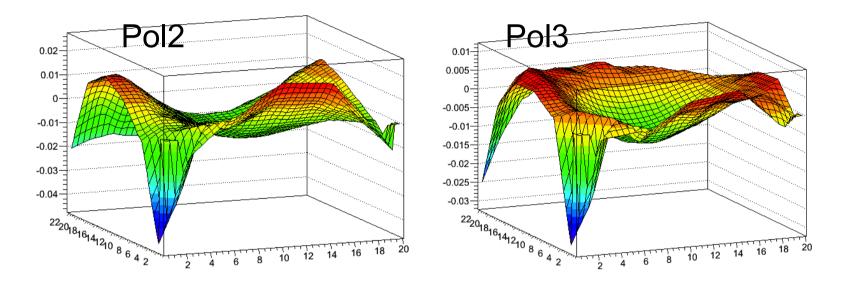


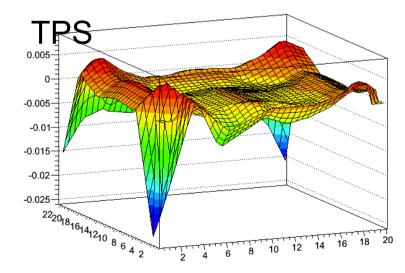




 $[0]+[1]^*x+[2]^*y+[3]^*x^*x+[4]^*y^*y+[5]^*x^*y+[6]^*x^*x^*x+[7]^*x^*x^*y+[8]^*x^*y^*y+[9]^*y^*y^*y$

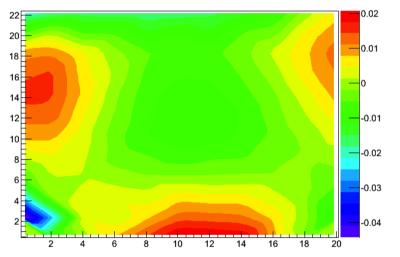


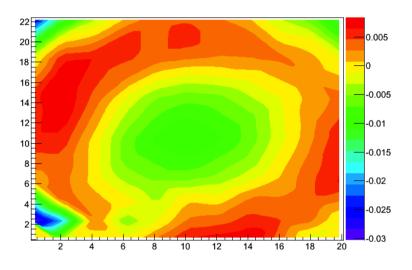




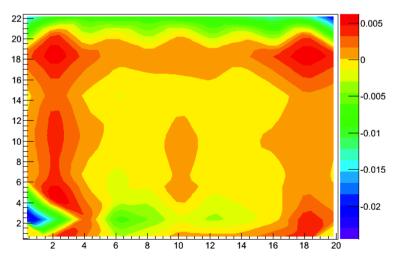
Pol2

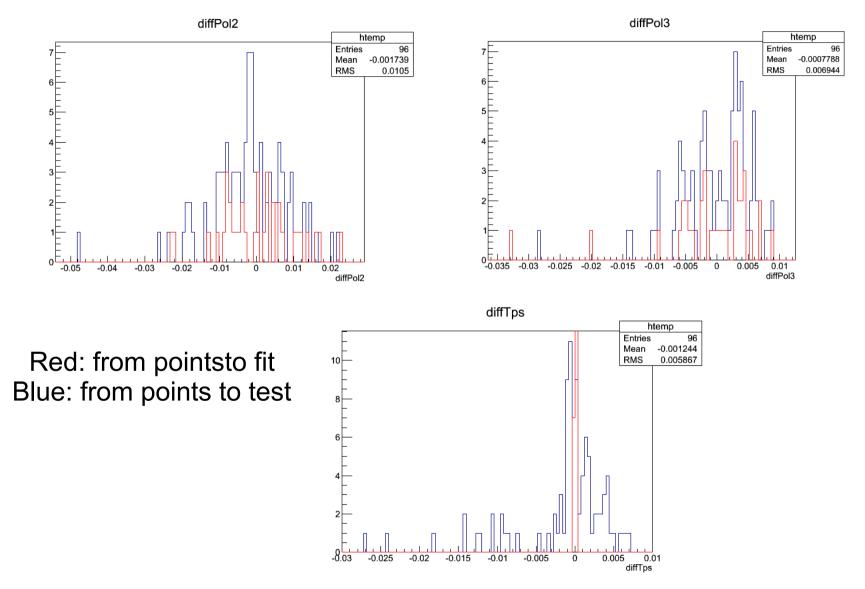
Pol3



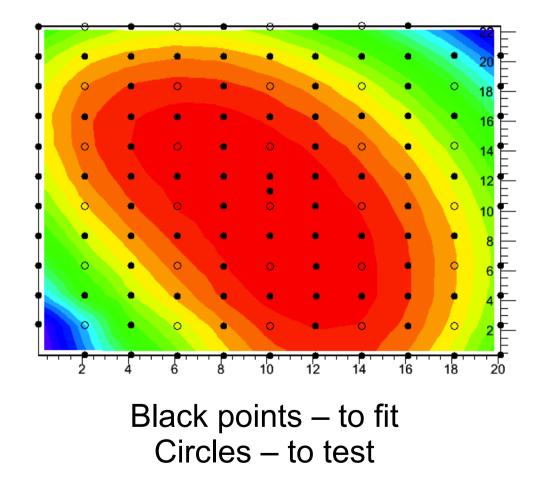


TPS



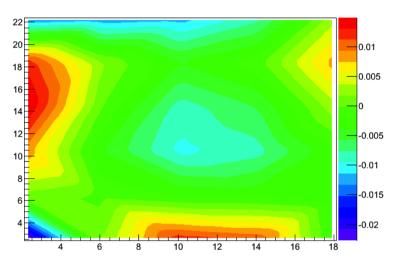


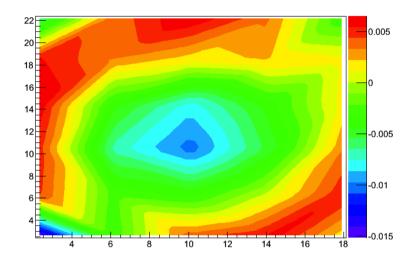
How about more points to fit?



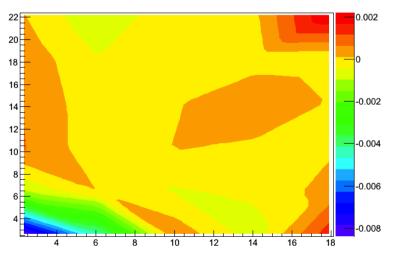
Pol2

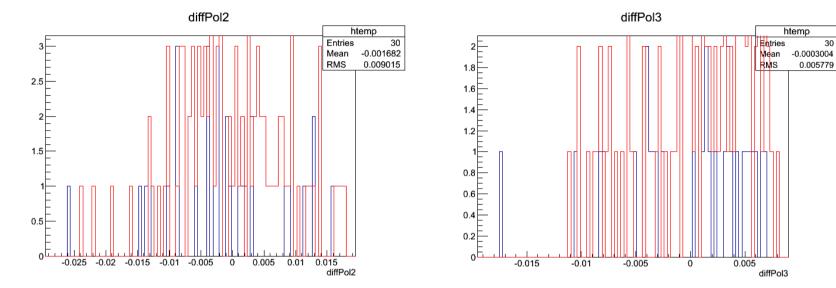
Pol3



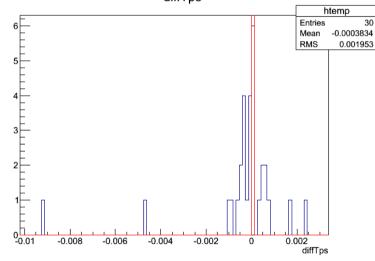


TPS





diffTps



30

Utilization of TPS

```
With n measurements of (x, y, z)
```

```
Fitting results need to calculate z(x, y):
a0, a1, a2, array x[n], y[n], w[n]
Size in DB and memory if n = 132:
(3+132*3)*10*4*10 ~ 160 k -----not a big deal
```

CPU time if n = 132: 0.088 s for 10 k hits (n hits for central 200 GeV AuAu without pile up) -----acceptable

Conclusion

- TPS does better than global pol2 and pol3 fit for a chip, and meets requirements on DB size and CPU time. The only backward is that it's not very straightforward.
- Piecewise interpolation/pol2 might do better than global pol2/pol3 fit, but require measurements on controlled (x, y) grids, which is only nearly true.
- TPS will yield ~< 1 µm difference for 132 measured points to fit
 ~< 5 µm difference for 36 measured points to fit
- The λ parameter in TPS, related to measurement errors, needs further study. Now $\lambda = 0$ is used, meaning measurement error = 0.
- $\Delta x(x, y)$, $\Delta y(x, y)$ from z(x, y) needs to be studied.